

Rosin Flux

835 is a rosin-based liquid flux with moderate activity. This rosin flux is composed of pure Water White (WW) grade gum rosin in a unique solvent system, combined with highly effective activators. Post-soldering residues from this RA liquid flux are non-conductive, non-corrosive, hygroscopic, non-tacky, and fungus resistant.

This rosin soldering flux can be used in both automated and manual soldering applications. It is great for general purpose soldering of PCBs, wire, cable, and semiconductors. It is also ideal for solder coating or tinning leads. It may be applied by spray, or foam for wave soldering applications.

Features & Benefits

Meets IPC J-STD-004B and type ROM1

For both leaded and lead-free solders

Fast wetting

Excellent foaming

RoHS-compliant

Storage and Handling

Store between 18 and 27 °C in a dry area, away from sunlight (see SDS).

Properties

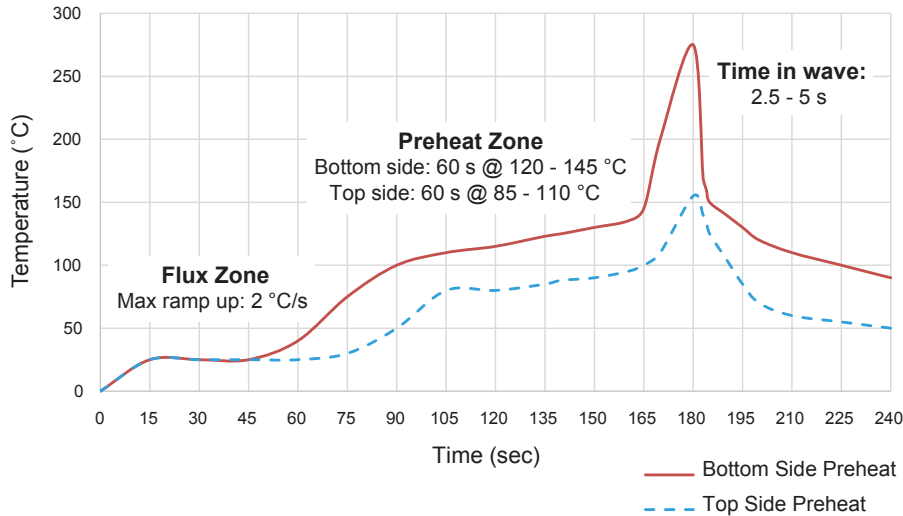
Color	Light amber	Visual
Solids %	50%	IPC-TM-650 2.3.34
Density	0.9 g/mL	—
Flux Classification	ROM1 RA	J-STD-004B, MIL-F-14256F
Flux Type	Rosin	J-STD-004B
Flux Activity	Moderate	J-STD-004B
Copper Mirror	Partial removal	IPC-TM-650 2.3.32
Corrosion Test	Pass	IPC-TM-650 2.6.15
Cleaning Requirements	Recommended	—
Halides (by weight)	0.44%	J-STD-004B
Shelf Life	5 y	—



Available Packaging

Part #	Packaging	Net Vol.	Net Wt.
835-100ML	Bottle	125 mL	116 g
835-100MLCA	Bottle	125 mL	116 g
835-1L	Bottle	1 L	930 g

Typical Lead-Free Wave Solder Profile



Application Instructions

Read the product SDS for more detailed instructions before using this product.

1. Apply flux on the surface by dip, spray, foam, or brush application.
2. Clean residue with MG 413B, 413C, 4140, 4050A, or 4140A flux removers.

Foam Flux

- The foam fluxer should be provided with the compressed air
- Flux tank must be always full
- Surface of the flux should be 0.5–1" above the top of the flux aerator or flux stone
- Adjust pressure to optimize foam height with a fine uniform foam head
- After fluxing, use an air knife to remove excess flux from the machine

To check for uniformity of spray flux coating, run a tempered glass plate provided by the machine manufacturer through the flux and preheat zones. Ensure to inspect the glass before the wave zone.

Wave Solder Operating Parameters

Amount of Flux	
Foam	1 000–2 000 µg/in ² solids
Spray	750–1 500 µg/in ² solids
Foam Fluxing Parameters	
Foam Stone Pore Size	20–50 µm
Flux Level Above Stone	25–40 mm
Chimney Opening	10–13 mm
Air Pressure	1–2 lb/in ²
Top Side Preheat Temp.	85–110 °C
Bottom Side Preheat Temp.	35 °C
Conveyor-speed	1.2–2.8 m/min
Contact Time in Solder	2.5–4.5 s
Solder Pot Temp.	
Sn96.5/Ag3.5	260–276 °C
Sn95/Ag5	280–296 °C
Sn99.3/Cu0.7	265–276 °C
SnAgCu	271–276 °C
Sn95/Sb5	280–296 °C

Disclaimer: This information is believed to be accurate. It is intended for professional end-users who have the skills required to evaluate and use the data properly. M.G. Chemicals Ltd. does not guarantee the accuracy of the data and assumes no liability in connection with damages incurred while using it.